

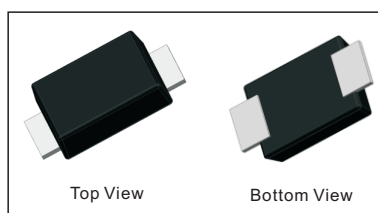


FEATURES

- RoHS compliant
- SMD type body size JD1410
- Large withstanding surge current capability : 200A (@8/20 μ s)
- Lower clamping voltage and excellent performance on ringing waves testing.
- Lead Free Finish/RoHS Compliant
- Green Molding Compound (No Halogen and Antimony)

MECHANICAL DATA

- Case: JD1410
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg/0.00095oz



Maximum Ratings and Thermal Characteristics(TA = 25°C unless otherwise specified)

Technology Data	Symbol	Value	Unit
Maximum allowable continuous AC voltage at 50-60Hz	V_{RMS}	150	V
Maximum allowable continuous DC voltage	V_{DC}	200	V
Maximum allowable clamping voltage	V_C	350	V
Maximum peak current (8/20 μ s)	I_{peak}	200	A
Operating Junction Temperature and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

NOTES:

1. The breakdown voltage was measured at 1mA
2. The clamping voltage was measured at 8/20 μ s standard current, (1A)
3. The peak current was tested at 8/20 μ s waveform

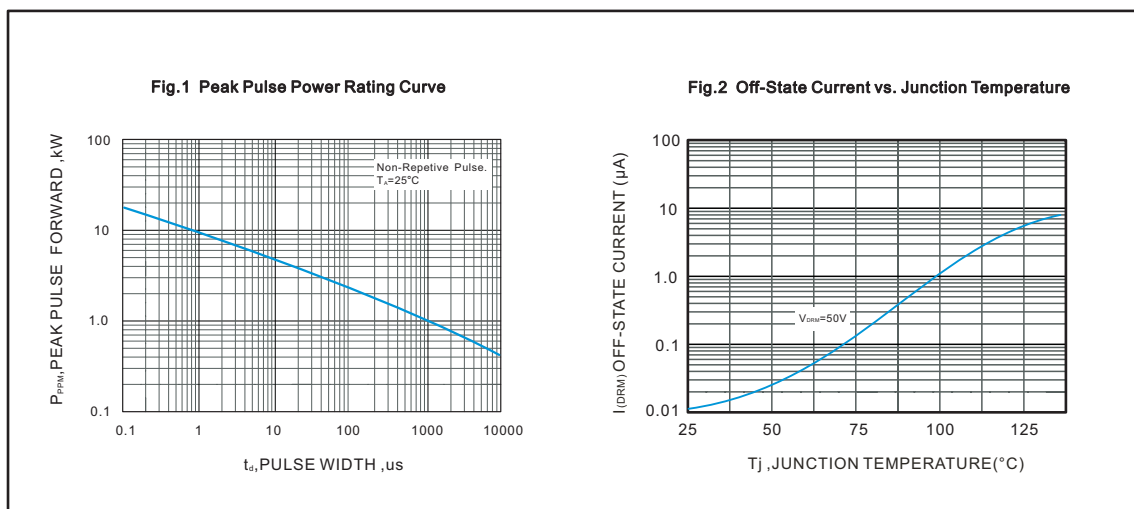




Fig.3 Derating Curve for number of pulses

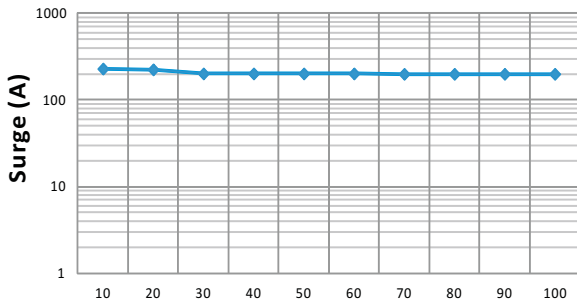


Fig.4 V/I Curve

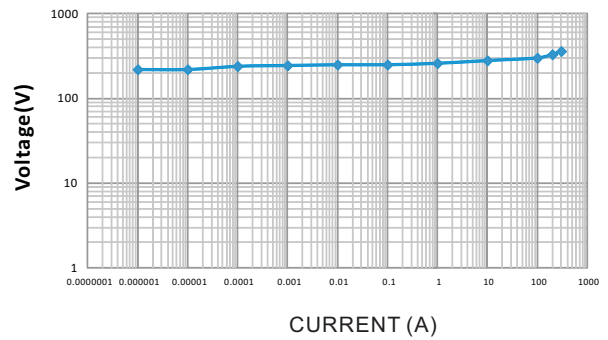
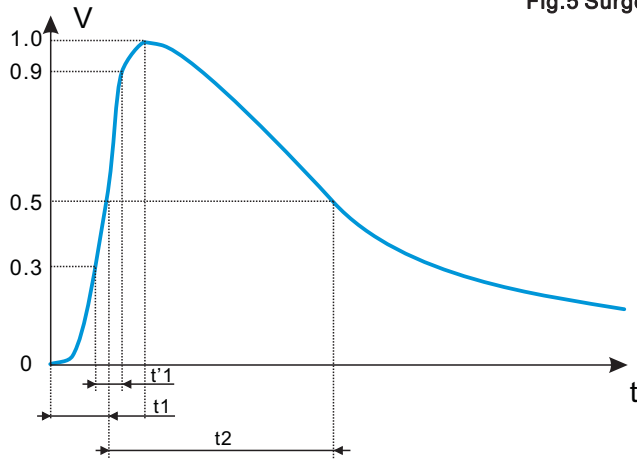


Fig.5 Surge Waveform

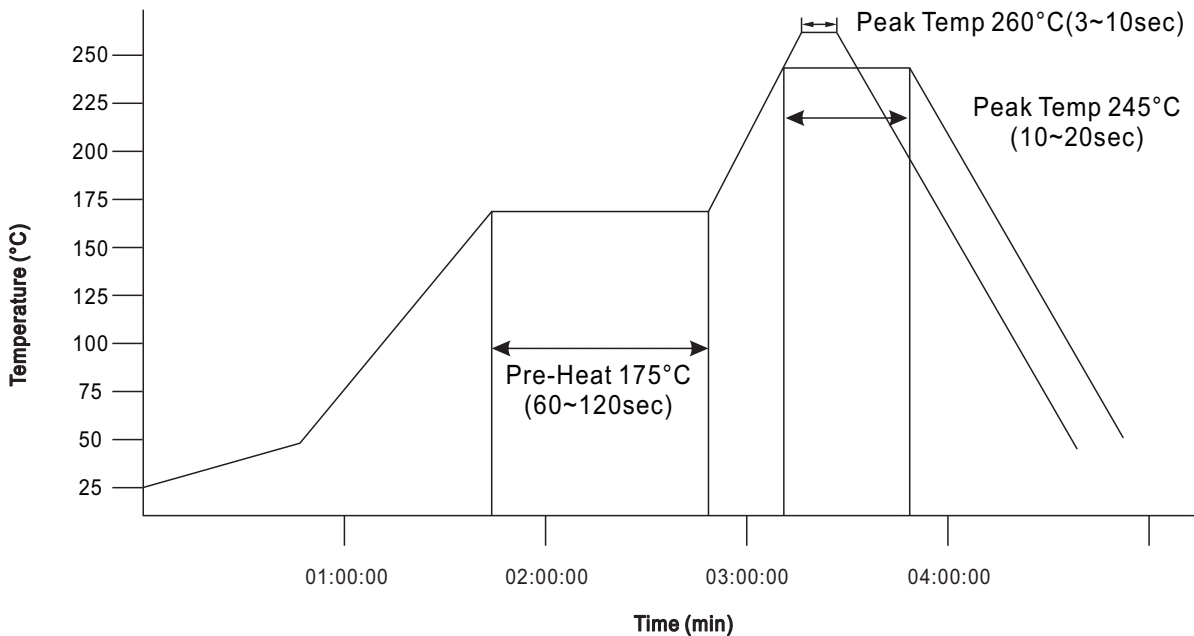


IEC61000-4-5 Standards

SEVERITY LEVEL	T1(=1.67t ₁)	T2
1	10us	1000us
2	8us	20us

8/20us waveform current

Fig.6 The IR reflow and temperature of soldering for Pb free process



IR reflow Pb free process suggestion profile:

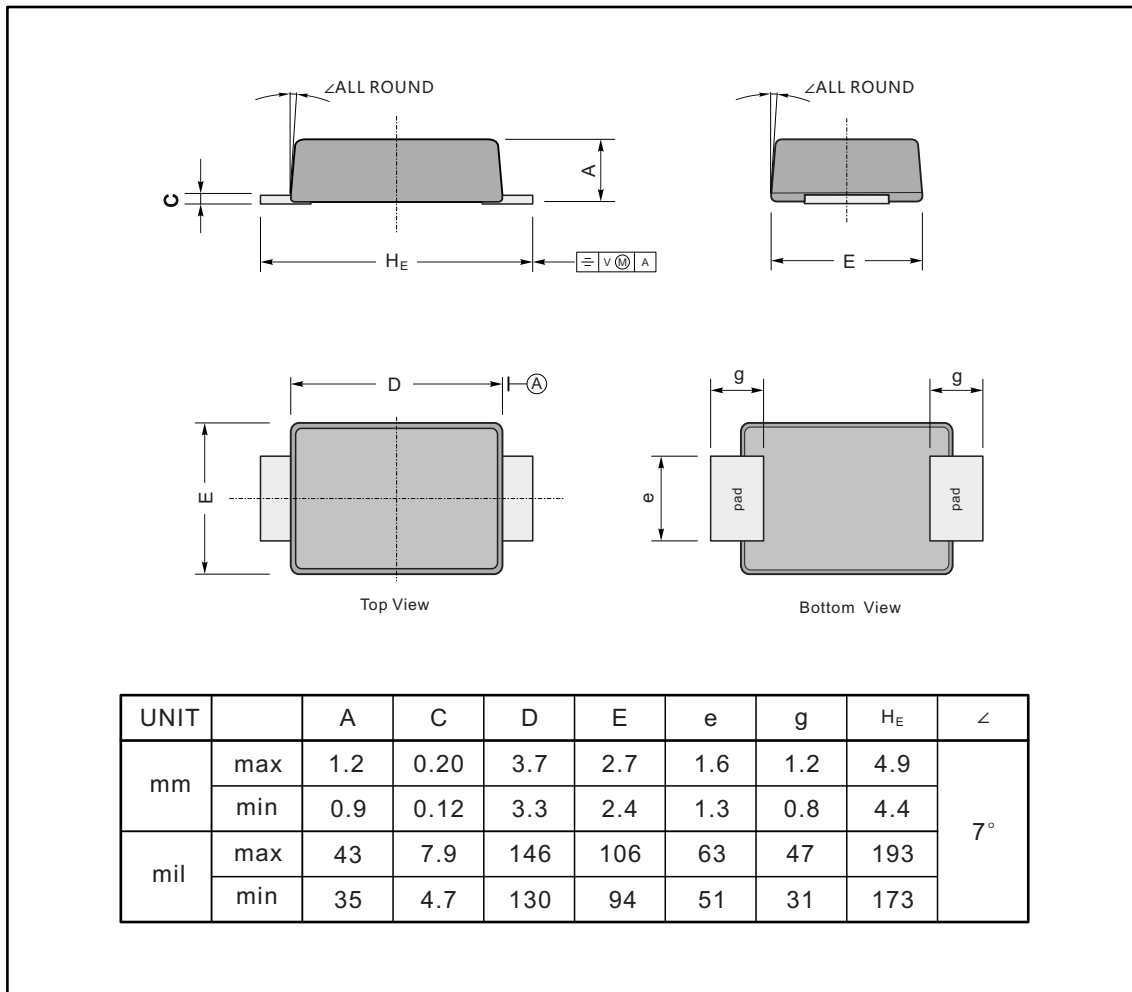
- (1) Ramp-up rate (217°C to peak) +3°C/second max.
- (2) Temp. maintain at 175±25 180seconds max.
- (3) Temp. maintain above 217°C 60~150 seconds
- (4) The peak temperature must be at least 260°C, the time above the 255°C must be within 20s



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

JD1410



The recommended mounting pad size

